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(71) Applicant : HITACHI LTD  
HITACHI MICRO COMPUT ENG LTD

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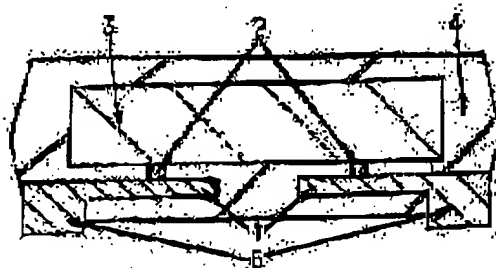
(72) Inventor : KANEMOTO KOICHI  
NISHIDA TAKAFUMI  
SUMIYA AKIRO

(54) SEMICONDUCTOR DEVICE

(57) Abstract:

PURPOSE: To reduce mounting area, and improve mounting efficiency in board mounting, by protruding a part of an inner lead from the bottom surface or the upper surface of a sealing resin part.

CONSTITUTION: An inner lead part 1 is electrically connected with a semiconductor chip 3 via a bump 2 formed on the inner lead part 1. An outer lead part 5 protruding from a resin molded part 4 is surface-mounted on a board or the like. By protruding a part of the inner lead from the bottom surface or the upper surface of the sealing resin part of a semiconductor device, the outer leads are provided in the area occupied by the sealing resin part of the semiconductor device, so that the mounting area is reduced and the mounting efficiency in the board mounting of a semiconductor device is improved.



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